

CLIPPEDIMAGE= JP359105349A

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TITLE: INTEGRATED CIRCUIT DEVICE

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ABSTRACT:

PURPOSE: To enable to manufacture an integrated circuit substrate which has many terminals and complicated functions with a small area and good yield at a low cost by a method wherein electrode terminals on the integrated circuit substrate are so arranged that the interval between connection members becomes almost constant.

CONSTITUTION: A pad  $d_{7}$  is set at the center of one side. Next, the value of a wire interval  $l$  is set at a value which satisfies the condition of wire bonding, pads  $d_{5}$  and  $d_{8}$  are decided by drawing a

triangle whose bottom side is a wire  $C</SB>7</SB>$  and height is 1. Further, pads  $d</SB>5</SB>$  and  $d</SB>9</SB>$  are decided by drawing a triangle whose bottom side is wires  $C</SB>6</SB>$  and  $C</SB>8</SB>$  and height is 1. The pads  $d</SB>1</SB>\sim d</SB>13</SB>$  are arranged in the above-mentioned manner, the value of the interval  $l$  is set again by evaluating its result, and the optimum arrangement is made by successive approximation with a computer. For example, the arrangement of 13 bonding pads  $d</SB>1</SB>\sim d</SB>13</SB>$  is made on one side of a chip, and, based on the optimum value, the pad intervals are successively enlarged toward each corner from the center of one side of the chip; thereby enabling the arrangement in such a manner that each wire interval becomes almost constant.

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